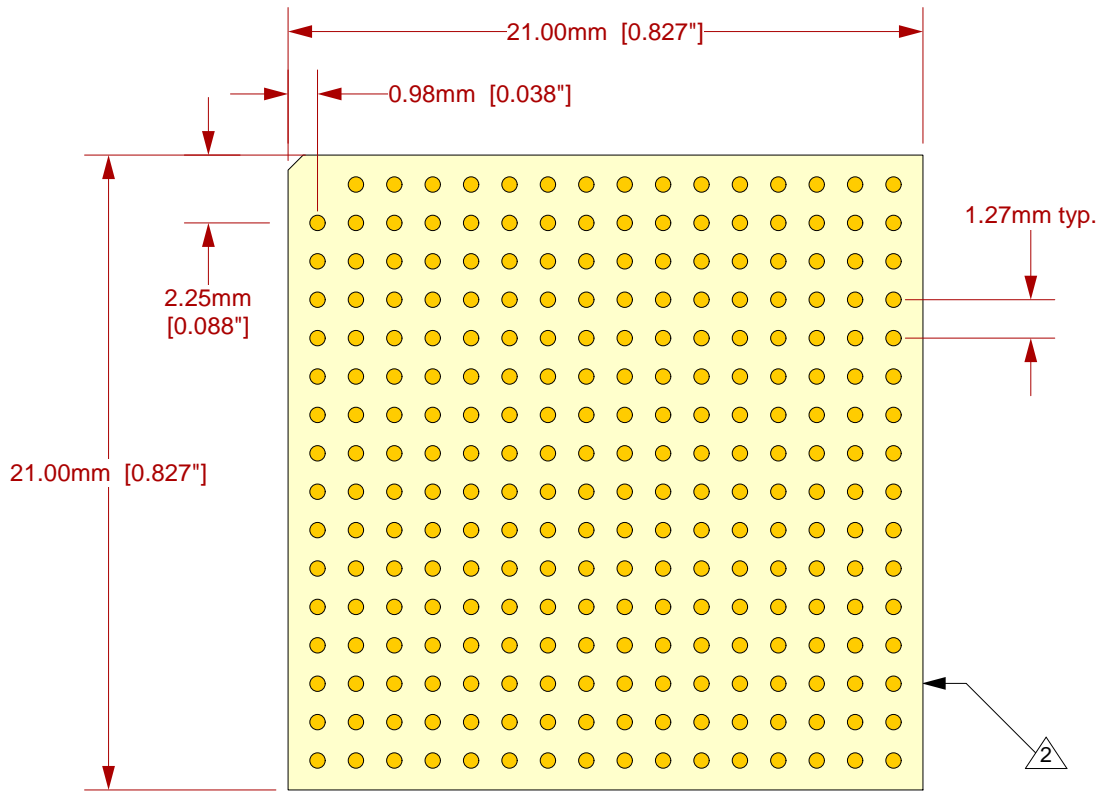
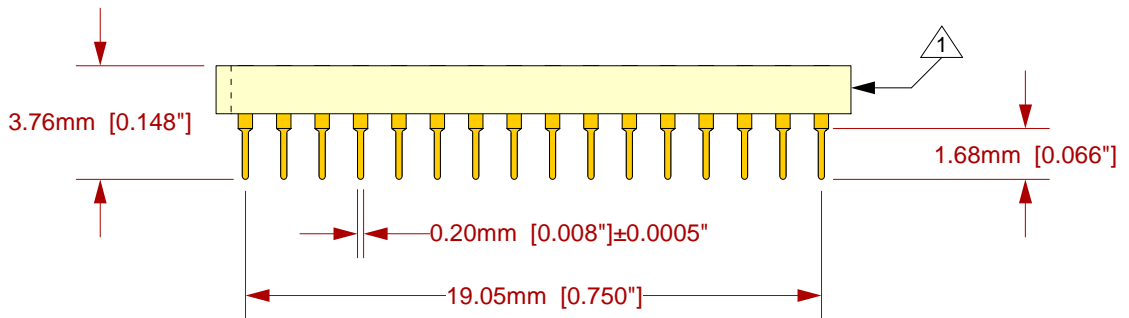


**Top View**



**Side View**




1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material.

2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).

**Description:** Giga-snaP BGA SMT Land Socket  
255 position BGA surface mount land pattern to terminal pins (1.27mm [0.050"] centers, 16x16 array)



**Tolerances:** diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

<b>LS-BGA255A-31 Drawing</b>		Status: Released	Scale: 4:1	Rev: A
 <p>© 2010 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	Drawing: M. Tully		Date: 8/2/10	
	File: LS-BGA255A-31 Dwg		Modified:	